



## NOT RECOMMENDED FOR NEW DESIGNS USE MMDT3904VC

**MMDT3904V** 

### **DUAL NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR**

### **Features**

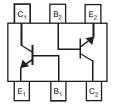
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Lead Free By Design/RoHS Compliant (Note 3)
- "Green" Device (Notes 4 and 5)

# **Mechanical Data**

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. (Note 5) UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe.
   Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Terminals: Lead Bearing Terminal Plating Available. See Ordering Information Page 3
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.003 grams (approximate)







Top View

**Bottom View** 

Device Schematic

## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Collector Current - Continuous	Ic	200	mA

# Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	$P_{D}$	200	mW
Thermal Resistance, Junction to Ambient	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

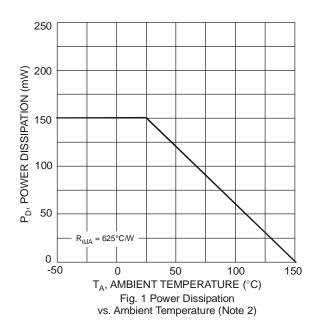
- 1. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).
- 2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead.
- 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.
- 5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

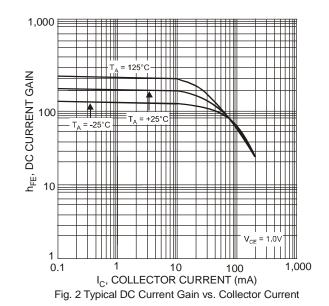


# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)					
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60		V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40		V	$I_C = 1.0 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	5.0		V	$I_E = 10\mu A, I_C = 0$
Collector Cutoff Current	I <sub>CEX</sub>		50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$
Base Cutoff Current	I <sub>BL</sub>		50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$
ON CHARACTERISTICS (Note 6)					
DC Current Gain	h <sub>FE</sub>	40 70 100 60 30	 300  	-	$I_C = 100\mu A, V_{CE} = 1.0V$ $I_C = 1.0mA, V_{CE} = 1.0V$ $I_C = 10mA, V_{CE} = 1.0V$ $I_C = 50mA, V_{CE} = 1.0V$ $I_C = 100mA, V_{CE} = 1.0V$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>		0.20 0.30	V	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.65	0.85 0.95	٧	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C <sub>obo</sub>	_	4.0	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0$
Input Capacitance	C <sub>ibo</sub>	_	8.0	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$
Input Impedance	h <sub>ie</sub>	1.0	10	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 1.0mA,$
Small Signal Current Gain	h <sub>fe</sub>	100	400		f = 1.0kHz
Output Admittance	h <sub>oe</sub>	1.0	40	μS	
Current Gain-Bandwidth Product	f⊤	300	_	MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz
Noise Figure	NF		5.0	dB	$V_{CE} = 5.0V, I_{C} = 100\mu A,$ $R_{S} = 1.0k\Omega, f = 1.0kHz$
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>d</sub>	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Rise Time	t <sub>r</sub>	_	35	ns	$V_{BE(off)} = -0.5V, I_{B1} = 1.0mA$
Storage Time	ts		200	ns	$V_{CC} = 3.0V, I_C = 10mA,$
Fall Time	t <sub>f</sub>	_	50	ns	$I_{B1} = I_{B2} = 1.0 \text{mA}$

Notes: 6. Short duration pulse test used to minimize self-heating effect.

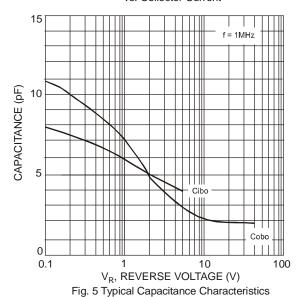






# VCE(SAT), COLLECTOR-EMITTER VCE(SAT), COLLECTOR-EMITTER SATURATION VOLTAGE (V) SATURATION VOLTAGE (

Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current



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# **MMDT3904V**

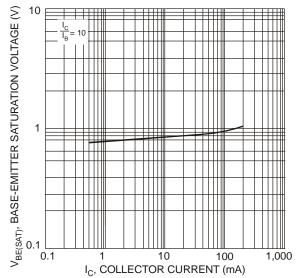


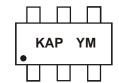
Fig. 4 Typical Base-Emitter Saturation Voltage vs. Collector Current

# Ordering Information (Note 7)

Part Number	Case	Packaging
MMDT3904V-7	SOT-563	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



KAP = Product Type Marking Code YM = Date Code Marking Y = Year (ex: R = 2004) M = Month (ex: 9 = September)

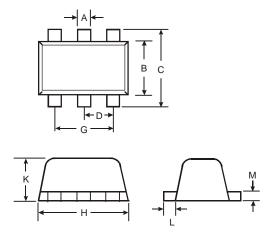
Date Code Key

Date Code Ney	′											
Year	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	R	S	Т	J	<b>V</b>	W	Χ	Υ	Z	Α	В	С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



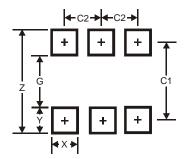


# **Package Outline Dimensions**



SOT-563					
Dim	Min	Max	Тур		
Α	0.15	0.30	0.20		
В	1.10	1.25	1.20		
С	1.55	1.70	1.60		
D	-	-	0.50		
G	0.90	1.10	1.00		
Н	1.50	1.70	1.60		
K	0.55	0.60	0.60		
L	0.10	0.30	0.20		
М	0.10	0.18	0.11		
All	All Dimensions in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



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**MMDT3904V** 

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